

【ABSTRACT】**CONDENSER MICROPHONE AND PACKAGING METHOD FOR THE SAME**

Disclosed are a silicone based condenser microphone comprising: a metal case which is a sound hole; a board which is mounted with a MEMS microphone chip and an ASIC chip having a electric voltage pump and a buffer IC and is formed with a connecting pattern for joining with the metal case; a fixing means for fixing the metal case to the board; and an adhesive for applying to the whole part where the metal case fixed to the board by the fixing means is joined with the board to bond the metal case to the board. Therefore, the metal case is tack-welded to the board by the laser to fix the case to the board and then bonds the case to the board with the adhesive, thereby decreasing an inferiority ratio and strengthening a joining force and thus enhancing a mechanical firmness and highly resisting noise from the outside.

[Figure 1]